

### FEATURES

- High Speed (Equal Access and Cycle Times)
  - 15/20/25 ns (Commercial)
  - 20/25/35 ns (Industrial)
  - 20/25/35/45/55/70 ns (Military)
- Low Power
- Single 5V±10% Power Supply
- Easy Memory Expansion Using  $\overline{CE}$  and  $\overline{OE}$  Inputs
- Common Data I/O
- Three-State Outputs
- Fully TTL Compatible Inputs and Outputs
- Advanced CMOS Technology
- Automatic Power Down
- Packages
  - 36-Pin SOJ (400 mil)
  - 36-Pin Flatpack
  - 32-Pin Gullwing Flatpack
  - 36-Pin LCC (452 mil x 920 mil)

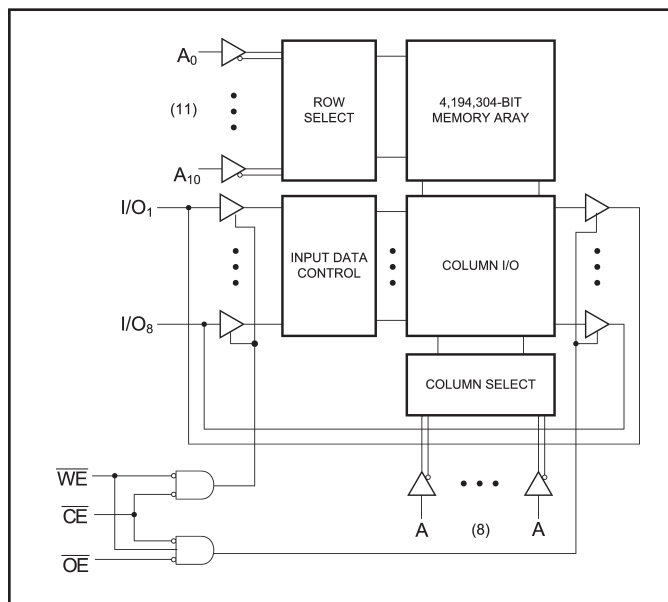
### DESCRIPTION

The P4C1049 is a 4 Megabit high-speed CMOS static RAM organized as 512Kx8. The CMOS memory requires no clocks or refreshing, and has equal access and cycle times. Inputs are fully TTL-compatible. The RAM operates from a single 5V±10% tolerance power supply.

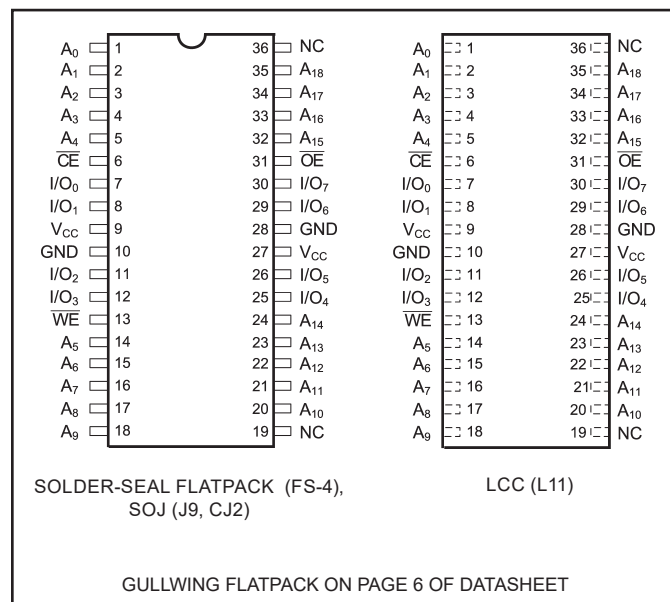
Access times as fast as 15 nanoseconds permit greatly enhanced system operating speeds. CMOS is utilized to reduce power consumption to a low level. The P4C1049 is a member of a family of PACE RAM™ products offering fast access times.

The P4C1049 device provides asynchronous operation with matching access and cycle times. Memory locations are specified on address pins  $A_0$  to  $A_{18}$ . Reading is accomplished by device selection ( $\overline{CE}$ ) and output enabling ( $\overline{OE}$ ) while write enable ( $\overline{WE}$ ) remains HIGH. By presenting the address under these conditions, the data in the addressed memory location is presented on the data input/output pins. The input/output pins stay in the HIGH Z state when either  $\overline{CE}$  or  $\overline{OE}$  is HIGH or  $\overline{WE}$  is LOW.

### FUNCTIONAL BLOCK DIAGRAM



### PIN CONFIGURATIONS





## MAXIMUM RATINGS<sup>(1)</sup>

Sym	Parameter	Value	Unit
V <sub>CC</sub>	Power Supply Pin with Respect to GND	-0.5 to +7	V
V <sub>TERM</sub>	Terminal Voltage with Respect to GND (up to 7.0V)	-0.5 to V <sub>CC</sub> + 0.5	V
T <sub>A</sub>	Operating Temperature	-55 to +125	°C
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>T</sub>	Power Dissipation	1.0	W
I <sub>OUT</sub>	DC Output Current	50	mA

## RECOMMENDED OPERATING CONDITIONS

Grade <sup>(2)</sup>	Ambient Temp	GND	V <sub>CC</sub>
Commercial	0°C to 70°C	0V	5.0V ± 10%
Industrial	-40°C to +85°C	0V	5.0V ± 10%
Military	-55°C to +125°C	0V	5.0V ± 10%

## CAPACITANCES<sup>(4)</sup>

(V<sub>CC</sub> = 5.0V, T<sub>A</sub> = 25°C, f = 1.0MHz)

Sym	Parameter	Conditions	Typ	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> =0V	8	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> =0V	8	pF

## DC ELECTRICAL CHARACTERISTICS

(Over Recommended Operating Temperature & Supply Voltage)<sup>(2)</sup>

Sym	Parameter	Test Conditions	P4C1049		P4C1049L		Unit	
			Min	Max	Min	Max		
V <sub>IH</sub>	Input High Voltage		2.2	V <sub>CC</sub> + 0.3	2.2	V <sub>CC</sub> + 0.3	V	
V <sub>IL</sub>	Input Low Voltage		-0.3 <sup>(3)</sup>	0.8	-0.3 <sup>(3)</sup>	0.8	V	
V <sub>HC</sub>	CMOS Input High Voltage		V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.3	V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.3	V	
V <sub>LC</sub>	CMOS Input Low Voltage		-0.3 <sup>(3)</sup>	0.2	-0.3 <sup>(3)</sup>	0.2	V	
V <sub>OL</sub>	Output Low Voltage (TTL Load)	I <sub>OL</sub> = +6 mA, V <sub>CC</sub> = Min		0.4		0.4	V	
V <sub>OH</sub>	Output High Voltage (TTL Load)	I <sub>OH</sub> = -4 mA, V <sub>CC</sub> = Min	2.4		2.4		V	
I <sub>LI</sub>	Input Leakage Current	V <sub>CC</sub> = Max, V <sub>IN</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	μA
			IND/COM	-5	+5	N/A	N/A	
I <sub>LO</sub>	Output Leakage Current	V <sub>CC</sub> = Max, CE = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	μA
			IND/COM	-5	+5	N/A	N/A	
I <sub>SB</sub>	Standby Power Supply Current (TTL Input Levels)	CE ≥ V <sub>IH</sub> , V <sub>CC</sub> = Max, f = Max, Outputs Open	MIL	—	45	—	40	mA
			IND/COM	—	40	—	N/A	
I <sub>SB1</sub>	Standby Power Supply Current (CMOS Input Levels)	CE ≥ V <sub>HC</sub> , V <sub>CC</sub> = Max, f = 0, Outputs Open V <sub>IN</sub> ≤ V <sub>LC</sub> or V <sub>IN</sub> ≥ V <sub>HC</sub>	MIL	—	15	—	10	mA
			IND/COM	—	10	—	N/A	

N/A = Not applicable

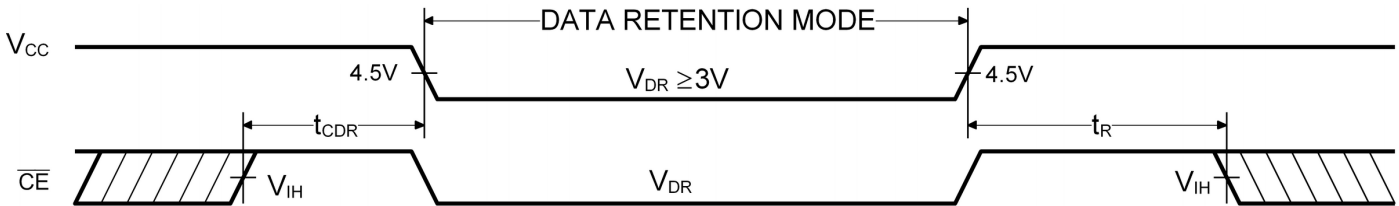
## DATA RETENTION CHARACTERISTICS (P4C1049L Military Temperature Only)

Sym	Parameter	Test Conditions	Min	Typ* $V_{CC} =$	Max $V_{CC} =$	Unit
				2.0V	2.0V	
$V_{DR}$	$V_{CC}$ for Data Retention		3.0			V
$I_{CCDR}$	Data Retention Current	$\overline{CE} \geq V_{CC} - 0.2V$ , $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$		2	3	mA
$t_{CDR}$	Chip Deselect to Data Retention Time		0			ns
$t_R^\dagger$	Operation Recovery Time		$t_{RC}^\S$			ns

\*  $T_A = +25^\circ C$ §  $t_{RC}$  = Read Cycle Time

† This Parameter is guaranteed but not tested

## DATA RETENTION WAVEFORM



## POWER DISSIPATION CHARACTERISTICS VS. SPEED

Sym	Parameter	Temperature Range	-15	-20	-25	-35	-45	-55	-70	Unit
$I_{CC}$	Dynamic Operating Current*	Commercial	220	185	180	N/A	N/A	N/A	N/A	mA
		Industrial	N/A	190	185	175	N/A	N/A	N/A	mA
		Military	N/A	200	195	185	175	170	165	mA

\*  $V_{CC} = 5.5V$ . Tested with outputs open.  $f = \text{Max}$ . Switching inputs are 0V and 3V.  $\overline{CE} = V_{IL}$ ,  $\overline{OE} = V_{IH}$ .

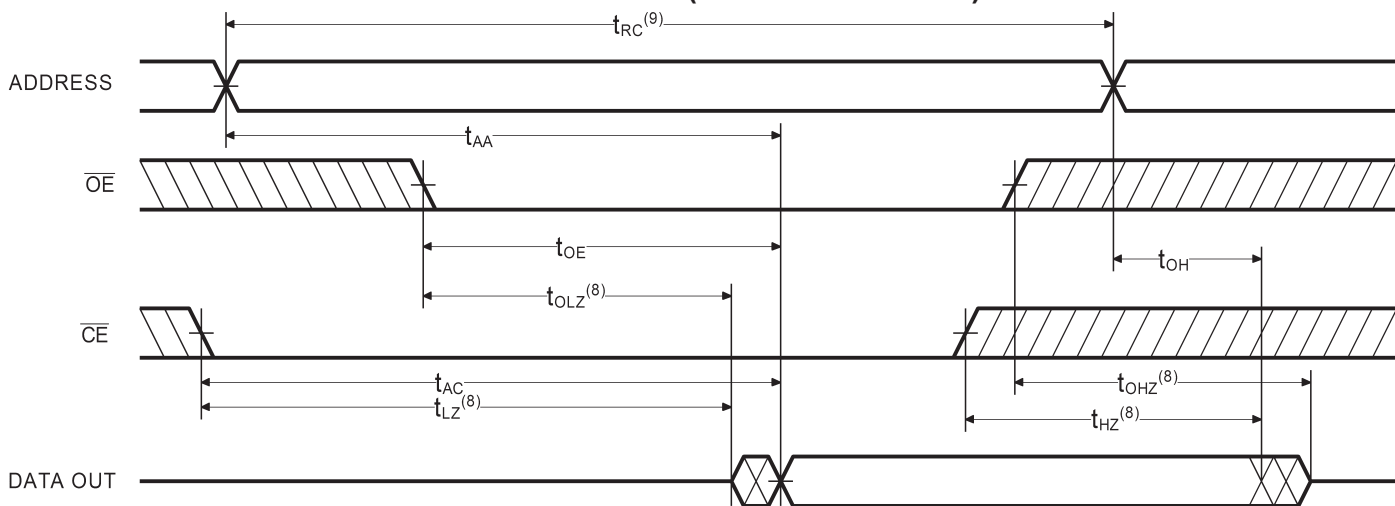
## AC ELECTRICAL CHARACTERISTICS—READ CYCLE

 $(V_{CC} = 5V \pm 10\%$ , All Temperature Ranges)<sup>(2)</sup>

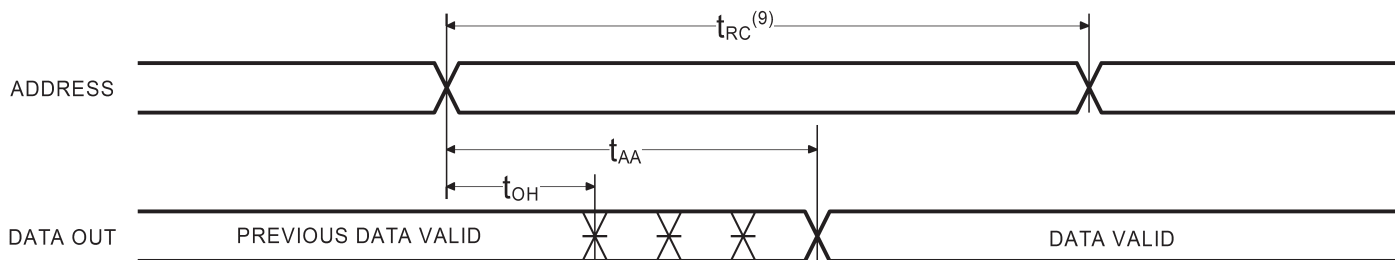
Sym	Parameter	-15		-20		-25		-35		-45		-55		-70		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{RC}$	Read Cycle Time	15		20		25		35		45		55		70		ns
$t_{AA}$	Address Access Time		15		20		25		35		45		55		70	ns
$t_{AC}$	Chip Enable Access Time		15		20		25		35		45		55		70	ns
$t_{OH}$	Output Hold from Address Change	3		3		3		3		3		3		3		ns
$t_{LZ}$	Chip Enable to Output in Low Z	3		3		3		3		3		3		3		ns
$t_{HZ}$	Chip Disable to Output in High Z		8		9		11		15		20		25		30	ns
$t_{OE}$	Output Enable Low to Data Valid		7		9		10		15		20		25		30	ns
$t_{OLZ}$	Output Enable Low to Low Z	0		0		0		0		0		0		0		ns
$t_{OHZ}$	Output Enable High to High Z		7		9		10		15		20		25		30	ns
$t_{PU}$	Chip Enable to Power Up Time	0		0		0		0		0		0		0		ns
$t_{PD}$	Chip Disable to Power Down Time		15		20		25		35		45		55		70	ns



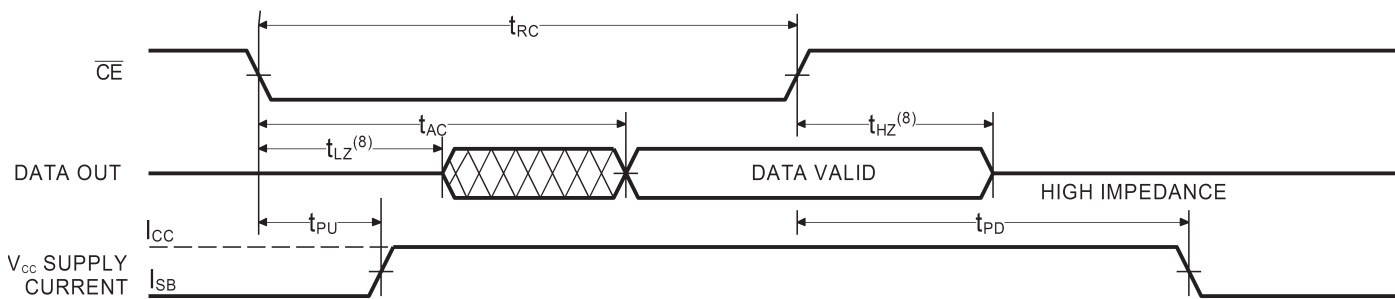
**TIMING WAVEFORM OF READ CYCLE NO. 1 ( $\overline{OE}$  CONTROLLED)<sup>(5)</sup>**



**TIMING WAVEFORM OF READ CYCLE NO. 2 (ADDRESS CONTROLLED)<sup>(5,6)</sup>**



**TIMING WAVEFORM OF READ CYCLE NO. 3 ( $\overline{CE}$  CONTROLLED)<sup>(5, 7)</sup>**





## AC CHARACTERISTICS—WRITE CYCLE

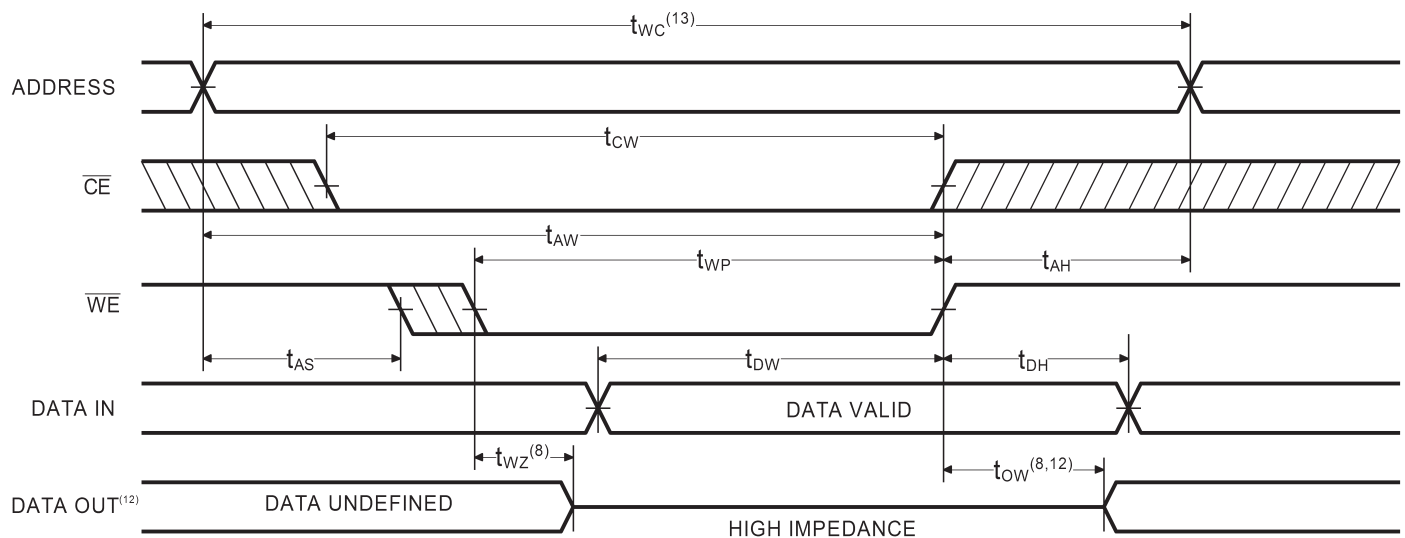
( $V_{CC} = 5V \pm 10\%$ , All Temperature Ranges)<sup>(2)</sup>

Sym	Parameter	-15		-20		-25		-35		-45		-55		-70		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{WC}$	Write Cycle Time	15		20		25		35		45		55		70		ns
$t_{CW}$	Chip Enable Time to End of Write	12		14		18		22		30		35		40		ns
$t_{AW}$	Address Valid to End of Write	12		14		16		20		25		35		40		ns
$t_{AS}$	Address Setup Time	0		0		0		0		0		0		0		ns
$t_{WP}$	Write Pulse Width	12		14		16		22		25		30		35		ns
$t_{AH}$	Address Hold Time	0		0		0		0		0		0		0		ns
$t_{DW}$	Data Valid to End of Write	9		11		13		15		20		25		30		ns
$t_{DH}$	Data Hold Time	0		0		0		0		0		0		0		ns
$t_{WZ}$	Write Enable to Output in High Z		8		10		11		15		18		25		30	ns
$t_{OW}$	Output Active from End of Write	3		3		3		5		5		5		5		ns

### Notes:

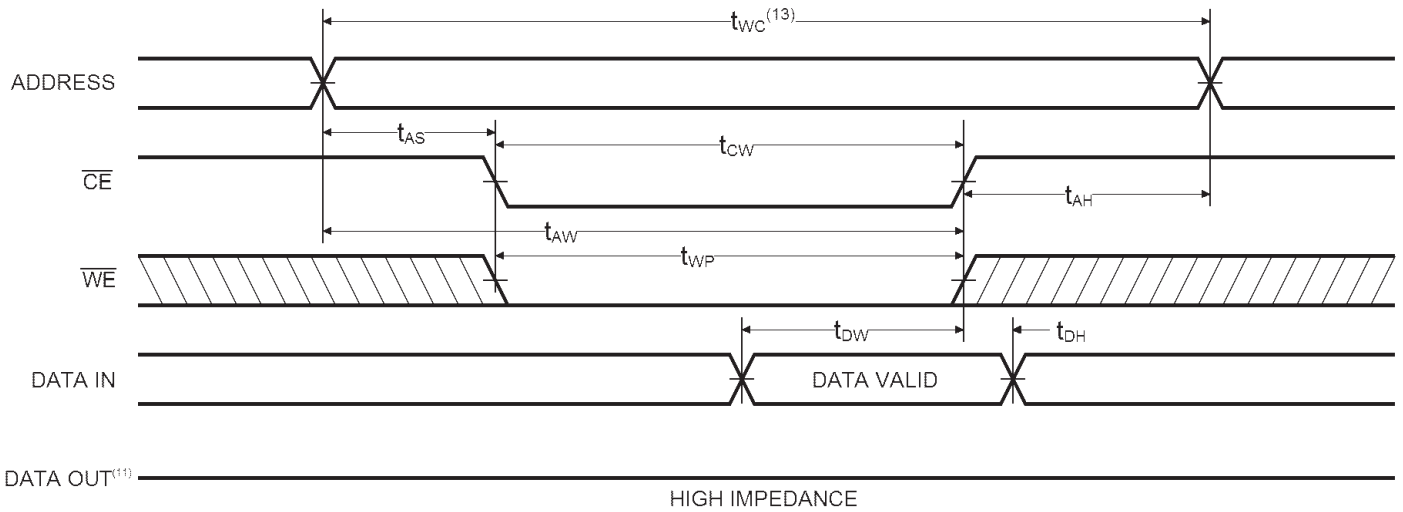
- Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to MAXIMUM rating conditions for extended periods may affect reliability.
- Extended temperature operation guaranteed with 400 linear feet per minute of air flow.
- Transient inputs with  $V_L$  and  $I_L$  not more negative than  $-2.0V$  and  $-100mA$ , respectively, are permissible for pulse widths up to 20ns.
- This parameter is sampled and not 100% tested.
- $\overline{WE}$  is HIGH for READ cycle.
- $\overline{CE}$  is LOW and  $\overline{OE}$  is LOW for READ cycle.
- ADDRESS must be valid prior to, or coincident with  $\overline{CE}$  transition LOW.
- Transition is measured  $\pm 200$  mV from steady state voltage prior to change, with loading as specified in Figure 1. This parameter is sampled and not 100% tested.
- Read Cycle Time is measured from the last valid address to the first transitioning address.

### TIMING WAVEFORM OF WRITE CYCLE NO. 1 ( $\overline{WE}$ CONTROLLED)<sup>(10,11)</sup>





### TIMING WAVEFORM OF WRITE CYCLE NO. 2 ( $\overline{CE}$ CONTROLLED)<sup>(10)</sup>



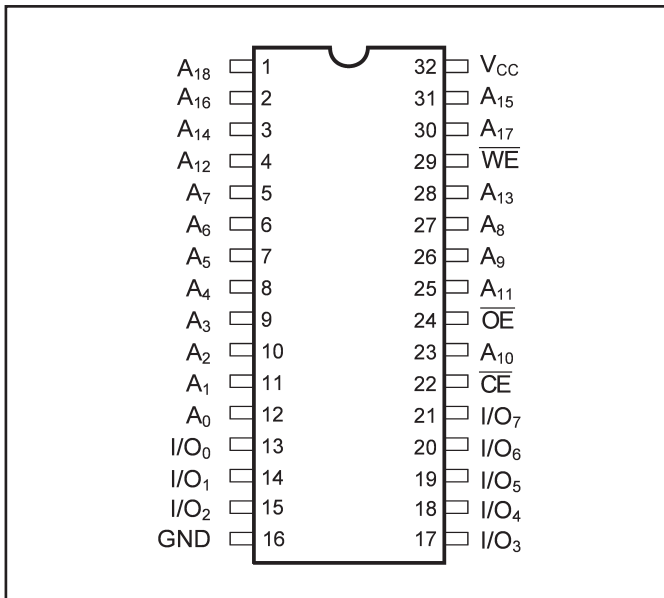
### AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Times	3ns
Input Timing Reference Level	1.5V
Output Timing Reference Level	1.5V
Output Load	See Figures 1 and 2

### TRUTH TABLE

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O	Power
Standby	H	X	X	High Z	Standby
$D_{OUT}$ Disabled	L	H	H	High Z	Active
Read	L	L	H	$D_{OUT}$	Active
Write	L	X	L	High Z	Active

### GULLWING FLATPACK PIN CONFIGURATION



Notes:

- 10.  $\overline{CE}$  and  $\overline{WE}$  must be LOW for WRITE cycle.
- 11.  $\overline{OE}$  is LOW for this WRITE cycle to show  $t_{wz}$  and  $t_{ow}$ .
- 12. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high impedance state

- 13. Write Cycle Time is measured from the last valid address to the first transitioning address.

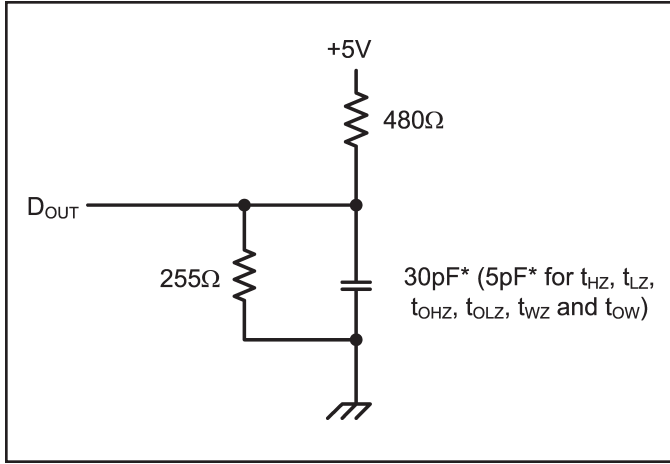


Figure 1. Output Load

\* including scope and test fixture.

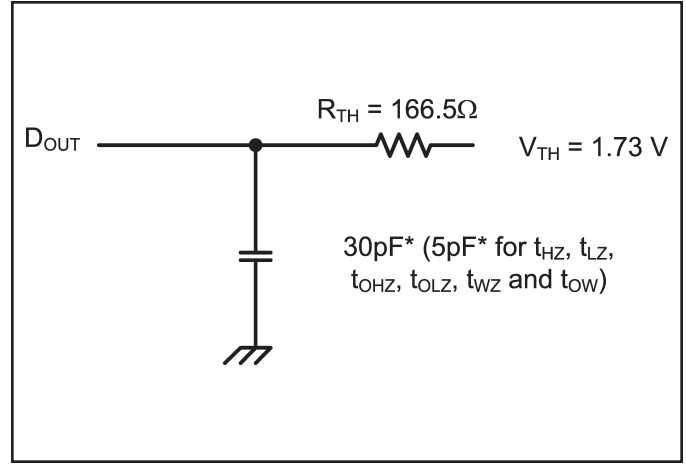


Figure 2. Thevenin Equivalent

**Note:**

Because of the ultra-high speed of the P4C1049/L, care must be taken when testing this device; an inadequate setup can cause a normal functioning part to be rejected as faulty. Long high-inductance leads that cause supply bounce must be avoided by bringing the V<sub>CC</sub> and ground planes directly up to the contactor fingers. A 0.01 μF high frequency capacitor

is also required between V<sub>CC</sub> and ground. To avoid signal reflections, proper termination must be used; for example, a 50Ω test environment should be terminated into a 50Ω load with 1.73V (Thevenin Voltage) at the comparator input, and a 116Ω resistor must be used in series with D<sub>OUT</sub> to match 166Ω (Thevenin Resistance).

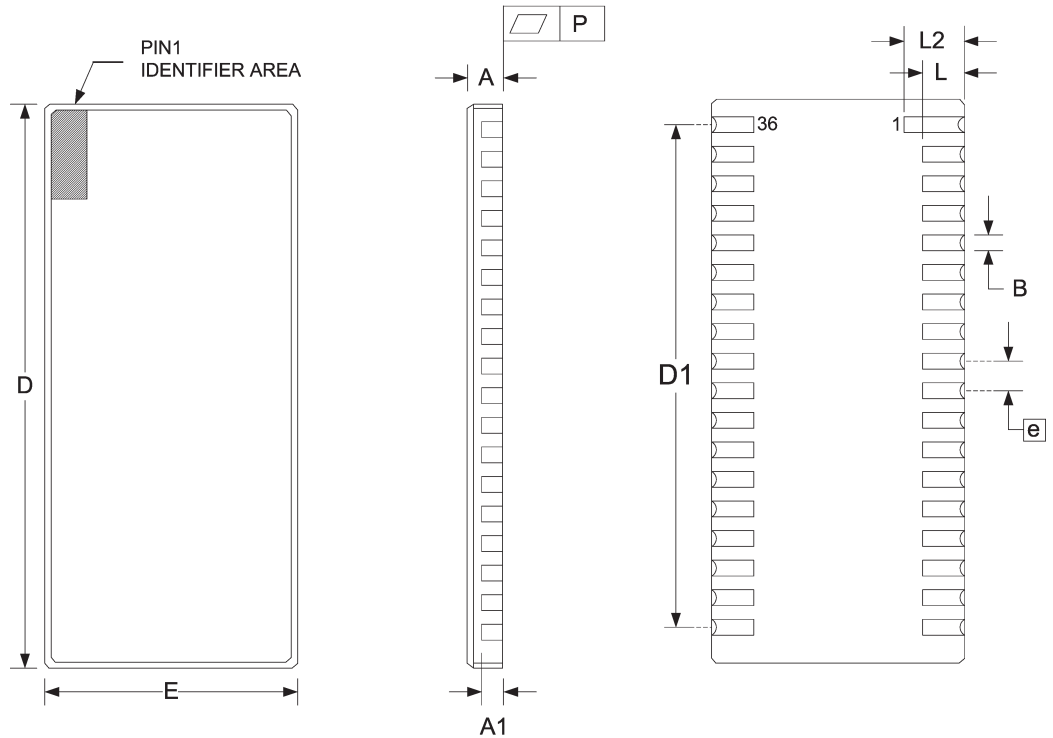
**ORDERING INFORMATION**

P4C1049	L	—	xx	x	x	
Device Type	Low Power		Speed	Package	Processing	
						C 0°C to +70°C
						I -40°C to +85°C
						M -55°C TO +125°C
						MB Mil. Temp with MIL-STD-883 Class B Compliance
						J SOJ
						L36 36-Pin Ceramic LCC (452 x 920 mil)
						FS36 36-Pin Solder Seal Flatpack
						TFS 32-Pin Gullwing Flatpack
						15, 20, 25, 35, 45, 55, 70 ns
						Low Power Designation (L=Low Power; Blank=None) <b>[Military Temperature Only]</b>
						512K x 8 SRAM



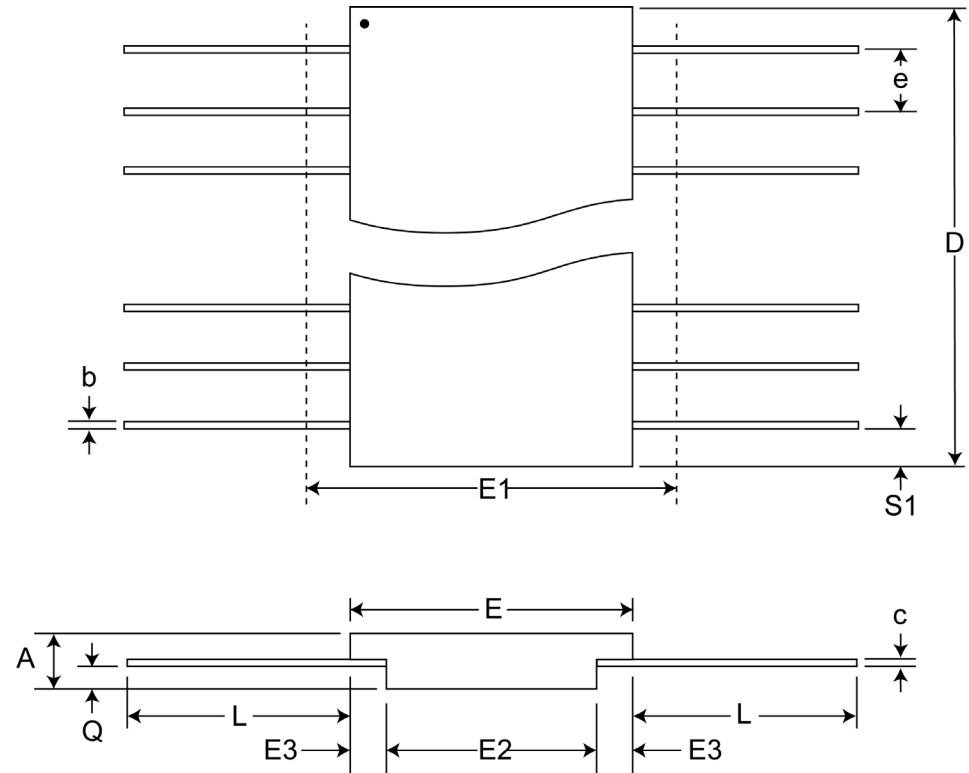
Pkg #	<b>L11</b>	
# Pins	36	
Symbol	Min	Max
A	0.080	0.100
A1	0.054	0.066
B	0.022	0.028
D	0.910	0.930
D1	0.840	0.860
E	0.445	0.460
e	.050 BSC	
L	.100 TYP	
L2	0.115	0.135
P	-	0.006
R	.009 TYP	

**RECTANGULAR LEADLESS CHIP CARRIER**



Pkg #	<b>FS-4</b>	
# Pins	36	
Symbol	Min	Max
A	0.089	0.125
b	0.015	0.019
c	0.003	0.007
D	0.910	0.930
E	0.505	0.515
E1	-	0.530
E2	0.385	0.395
E3	0.055	0.065
e	0.050 BSC	
L	0.300	0.350
Q	0.015	0.038
S	-	0.045
M	-	0.002
N	36	

**SOLDER SEAL FLATPACK**

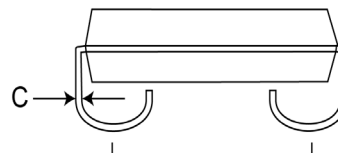
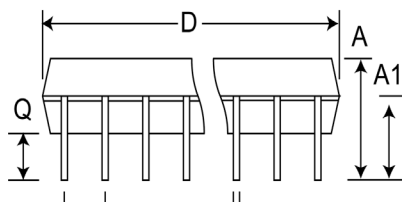
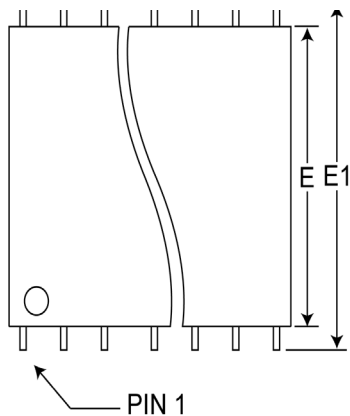






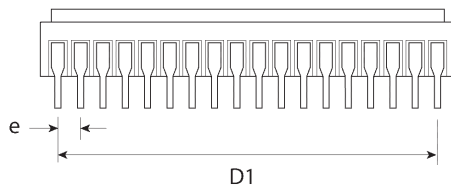
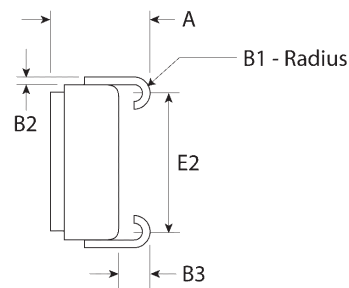
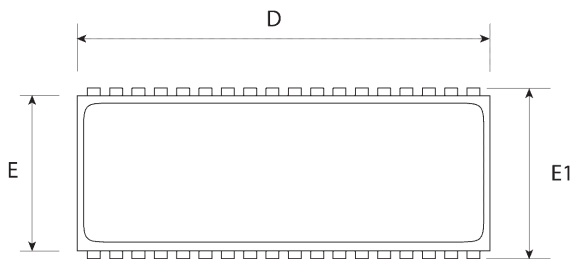
### SOJ SMALL OUTLINE IC PACKAGE

Pkg #	<b>J9</b>	
# Pins	36	
Symbol	<b>Min</b>	<b>Max</b>
A	0.130	0.145
A1	0.082	-
b	0.015	0.020
C	0.007	0.013
D	0.920	0.930
e	0.050 BSC	
E	0.435	0.445
E1	0.395	0.405
E2	0.370 BSC	
Q	0.045	0.055



### CERAMIC SOJ SMALL OUTLINE IC PACKAGE

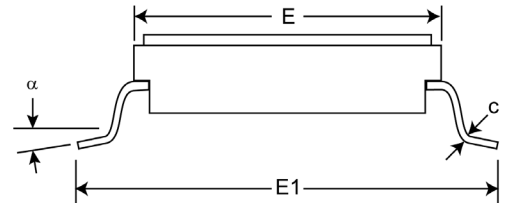
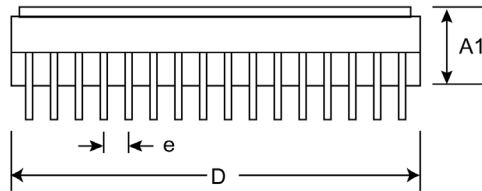
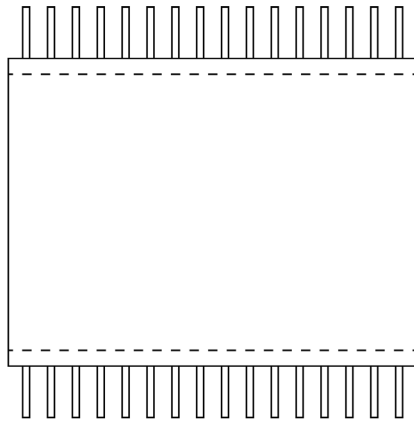
Pkg #	<b>CJ2</b>	
# Pins	36	
Symbol	<b>Min</b>	<b>Max</b>
A	0.120	0.165
B1	0.030R TYP	
B2	0.020 REF	
B3	0.025	0.045
D	0.816	0.838
E	0.419	0.431
E2	0.360	0.380
e	0.050 BSC	
E1	0.430	0.454





Pkg #	<b>S13</b>	
# Pins	32	
Symbol	<b>Min</b>	<b>Max</b>
A1	88	118
D	860	880
e	.050 BSC	
E	404	416
E1	559	567
$\alpha$	0°	8°

**GULLWING FLATPACK**



**REVISIONS**

<b>DOCUMENT NUMBER</b>	SRAM 128
<b>DOCUMENT TITLE</b>	P4C1049/P4C1049L - HIGH SPEED 512K X 8 STATIC CMOS RAM

<b>REV</b>	<b>ISSUE DATE</b>	<b>ORIGINATOR</b>	<b>DESCRIPTION OF CHANGE</b>
OR	Oct-2005	JDB	New Data Sheet
A	Jan-2008	JDB	Added CJ2 Ceramic SOJ Package
B	Mar-2009	JDB	Added C10 Ceramic DIP Package
C	Aug-2011	JDB	Corrected typo in package list
D	Sep-2019	JDB	Update DC Electrical Characteristics table; removed 32-pin ceramic DIP
E	Oct-2019	JDB	Added 32 pin Gullwing Flatpack